

BATCH REFLOW OVEN WITH FORCED AIR CONVECTION - FT 03

FT03 oven has been conceived to the reflow of solder paste or polymerization of the glues for prototyping.

FT03 oven is compatible with high temperature alloys and above all "lead free" ones thanks to its new heating system as well as its electronics.



It includes in line many functions as 10 programs memorization, information display upon LCD monitor, a viewing window to supervise the process.

- View of the card thanks to a large window on the front panel
- Possibility to keep in memory 10 programs
- Compact model, but working area of **190 x 290 mm**
- Heating through forced convection
- Temperature control by microprocessor, **max. T° 300°C**
- Digital display of different advises: temperature and time
- Easy programming for immediate control
- Safety: double window with air circulation, closing door access

Technical data

Model	FT03
Working area:	190 mm x 290 mm
Heating:	2 levels
Quartz heating elements:	2 x 1 KW
Temperature control:	by microprocessor
Max Temperature:	up to 300°C
Thermic stabilisation time:	about 3 minutes
Noise level:	< 50 dBA
Electrical Supply:	230 V -50/60Hz
Net weight:	19 Kg

Reference **V900320**

